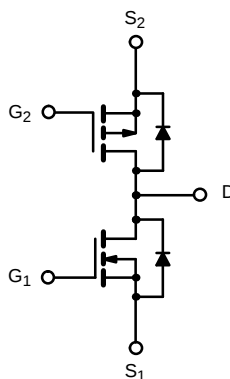
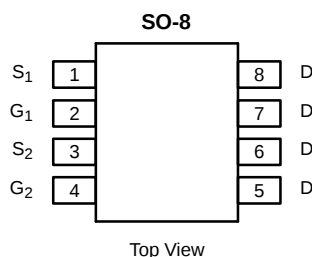




N-/P-Channel, Reduced Q_g , Fast Switching Half-Bridge

High-Efficiency
PWM Optimized

PRODUCT SUMMARY			
	V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
N-Channel	20	0.055 @ $V_{GS} = 4.5$ V	± 4.5
		0.075 @ $V_{GS} = 3.0$ V	± 3.8
P-Channel	-20	0.080 @ $V_{GS} = -4.5$ V	± 4.0
		0.120 @ $V_{GS} = -3.0$ V	± 3.0



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)				
Parameter		Symbol	N-Channel	P-Channel
Drain-Source Voltage		V_{DS}	20	-20
Gate-Source Voltage		V_{GS}	± 14	
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	$T_A = 25^\circ\text{C}$	I_D	± 4.5	± 4.0
	$T_A = 70^\circ\text{C}$		± 3.6	± 3.0
Pulsed Drain Current		I_{DM}	± 20	
Continuous Source Current (Diode Conduction) ^a		I_S	1.7	-1.7
Maximum Power Dissipation ^a	$T_A = 25^\circ\text{C}$	P_D	2.0	
	$T_A = 70^\circ\text{C}$		1.3	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 150	

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	N- or P-Channel	Unit
Maximum Junction-to-Ambient ^a	R_{thJA}	62.5	$^\circ\text{C/W}$

Notes

a. Surface Mounted on FR4 Board, $t \leq 10$ sec.

SPECIFICATIONS (T _J = 25 °C UNLESS OTHERWISE NOTED)								
Parameter	Symbol	Test Condition		Min	Typ	Max	Unit	
Static								
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	N-Ch	0.6			V	
		V _{DS} = V _{GS} , I _D = −250 μA	P-Ch	−0.6				
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±12 V	N-Ch P-Ch			±100 ±100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V	N-Ch			1	μA	
		V _{DS} = −20 V, V _{GS} = 0 V	P-Ch			−1		
		V _{DS} = 20 V, V _{GS} = 0 V, T _J = 70 °C	N-Ch			25		
		V _{DS} = −20 V, V _{GS} = 0 V, T _J = 70 °C	P-Ch			−25		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 4.5 V	N-Ch	20			A	
		V _{DS} = −5 V, V _{GS} = −4.5 V	P-Ch	−20				
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 4.5 V, I _D = 4.5 A	N-Ch		0.044	0.055	Ω	
		V _{GS} = −4.5 V, I _D = −4.0 A	P-Ch		0.064	0.080		
		V _{GS} = 3.0 V, I _D = 3.8 A	N-Ch		0.055	0.075		
		V _{GS} = −3.0 V, I _D = −3.0 A	P-Ch		0.086	0.120		
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 4.5 A	N-Ch		11.5		S	
		V _{DS} = −15 V, I _D = −4.0 A	P-Ch		9.8			
Diode Forward Voltage ^a	V _{SD}	I _S = 1.7 A, V _{GS} = 0 V	N-Ch		0.73	1.2	V	
		I _S = −1.7 A, V _{GS} = 0 V	P-Ch		−0.75	−1.2		
Dynamic ^b								
Total Gate Charge	Q _g	N-Channel V _{DS} = 3.5 V, V _{GS} = 4.5 V, I _D = 0.8 A P-Channel V _{DS} = −3.5 V, V _{GS} = −4.5 V I _D = −0.8 A	N-Ch		5.2	10	nC	
Gate-Source Charge	Q _{gs}		P-Ch		7.9	15		
Gate-Drain Charge	Q _{gd}		N-Ch P-Ch		1.15 1.90			
Turn-On Delay Time	t _{d(on)}	N-Channel V _{DD} = 3.5 V, R _L = 4.3 Ω I _D ≅ 0.8 A, V _{GEN} = 4.5 V, R _G = 6 Ω P-Channel V _{DD} = −3.5 V, R _L = 4.3 Ω I _D ≅ −0.8 A, V _{GEN} = −4.5 V, R _G = 6 Ω	N-Ch P-Ch		12 20	20 40	ns	
Rise Time	t _r		N-Ch P-Ch		22 52	50 90		
Turn-Off Delay Time	t _{d(off)}		N-Ch P-Ch		27 37	50 60		
Fall Time	t _f		N-Ch P-Ch		8 11	20 20		
Source-Drain Reverse Recovery Time	t _{rr}		N-Channel—I _F = 1.7 A, di/dt = 100 A/μs P-Channel—I _F = −1.7 A, di/dt = 100 A/μs	N-Ch P-Ch		60 60		100 100

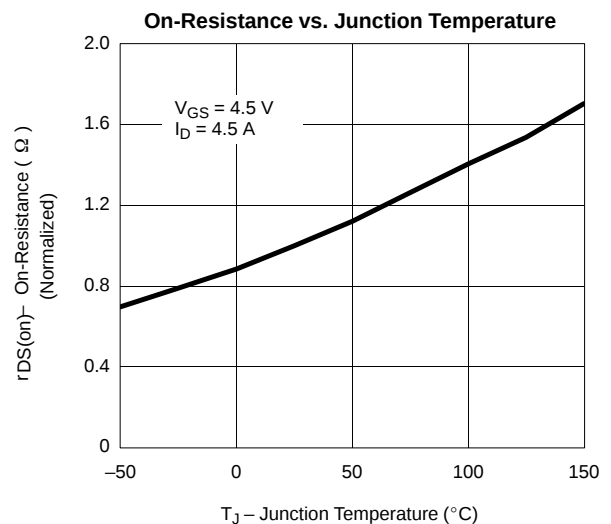
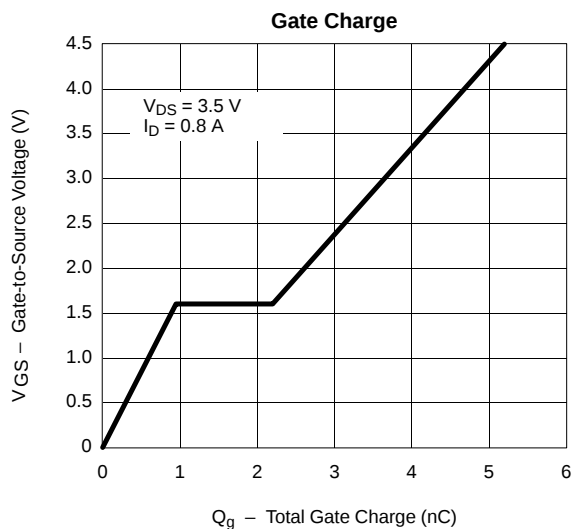
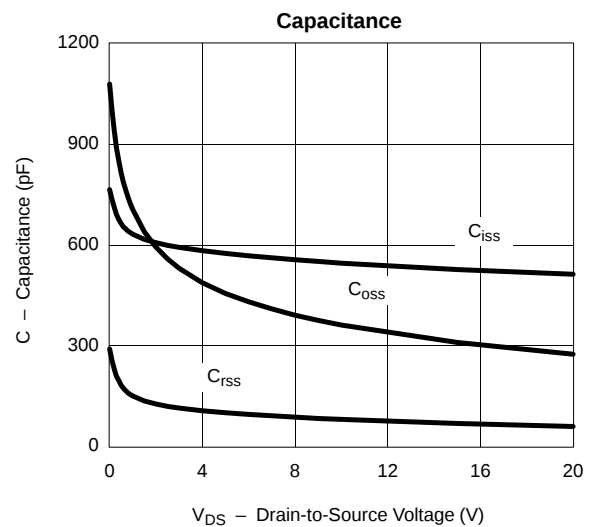
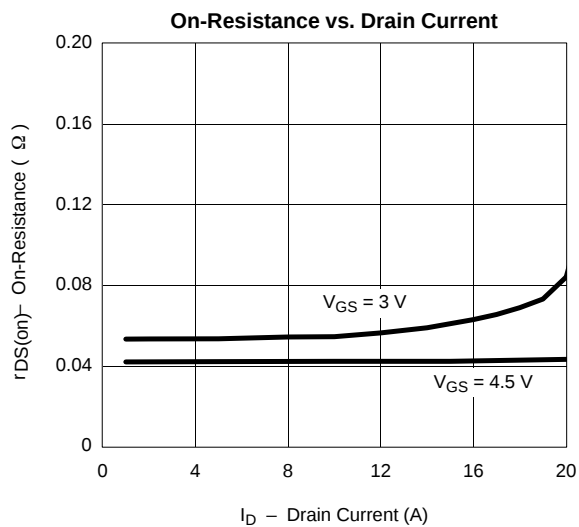
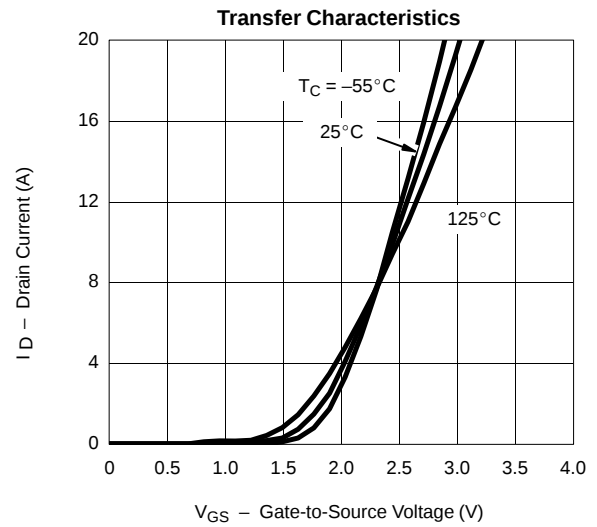
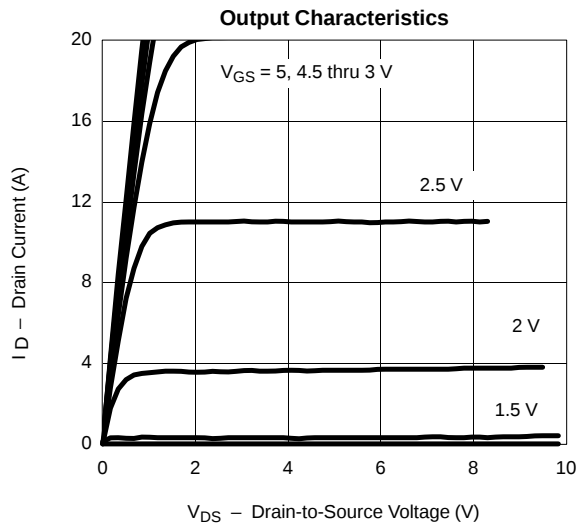
Notes

- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
b. Guaranteed by design, not subject to production testing.



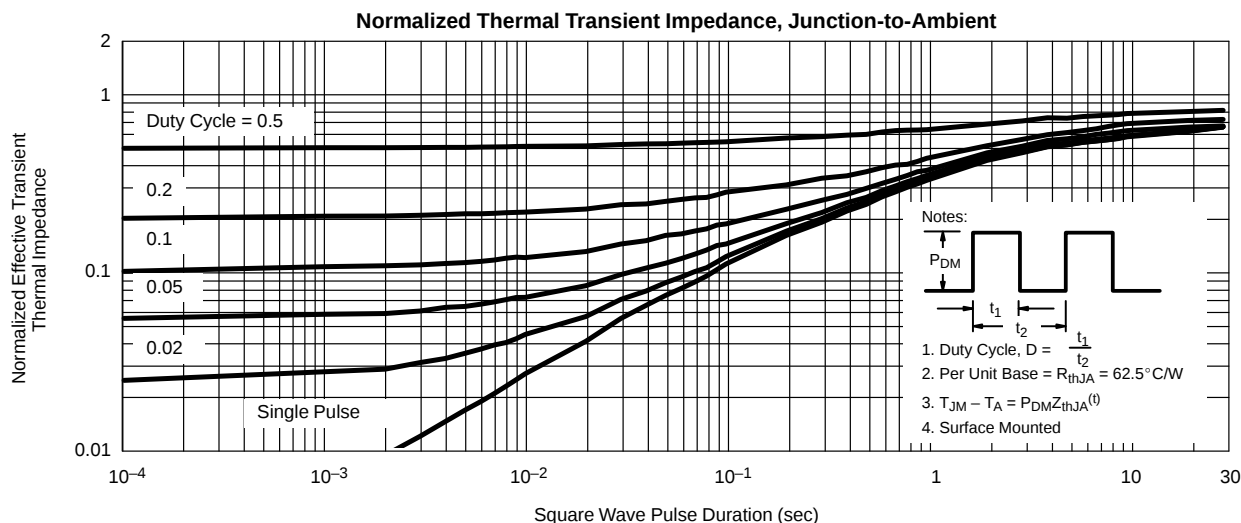
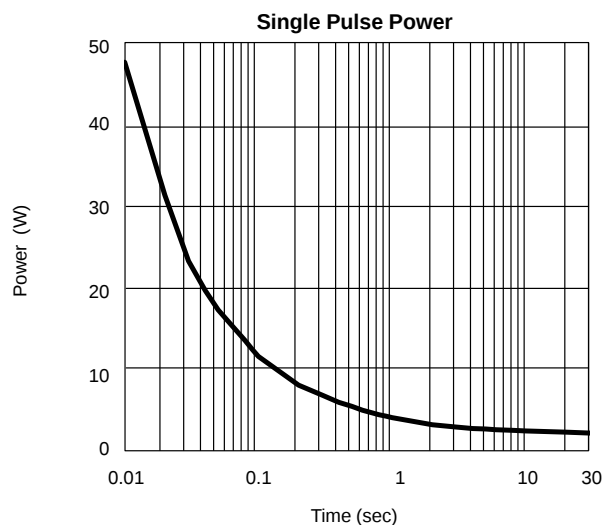
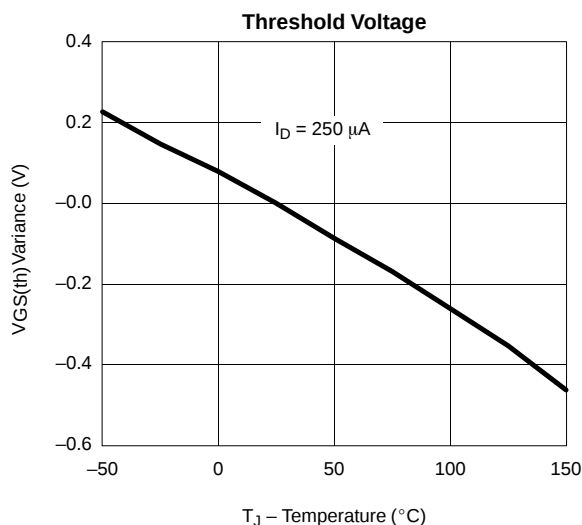
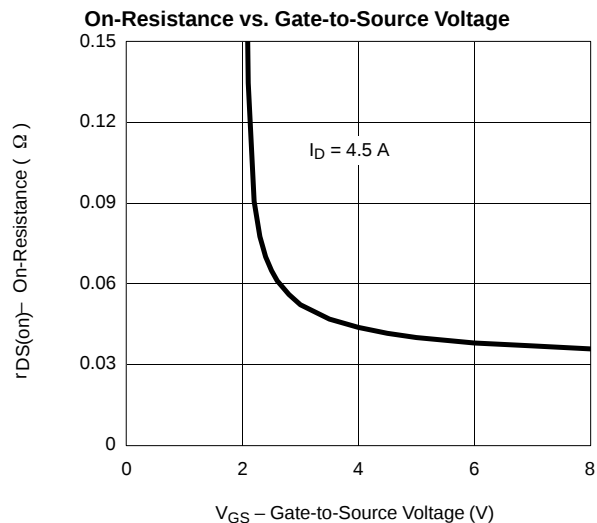
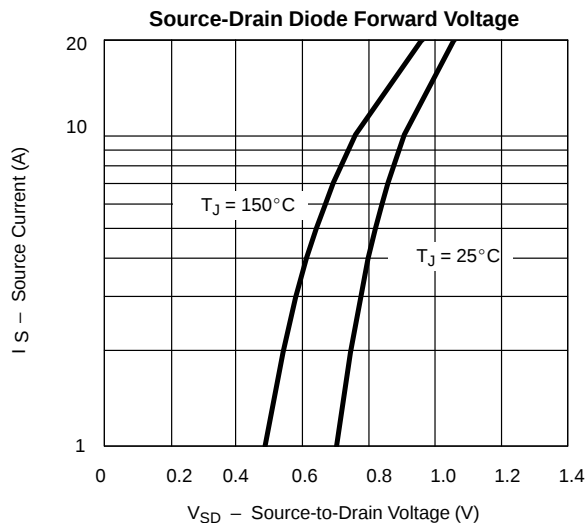
TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

N-CHANNEL



TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

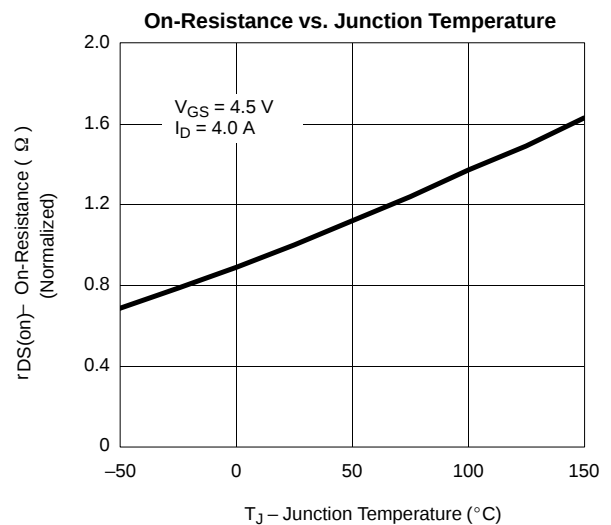
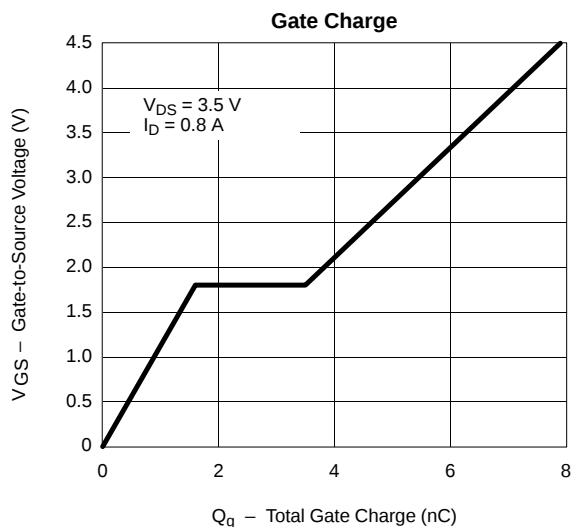
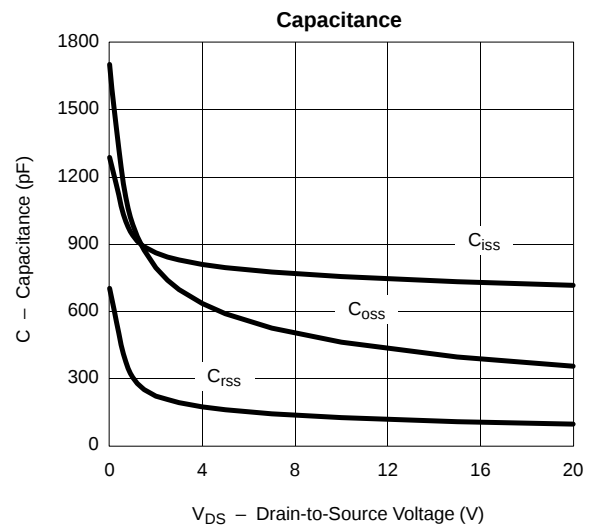
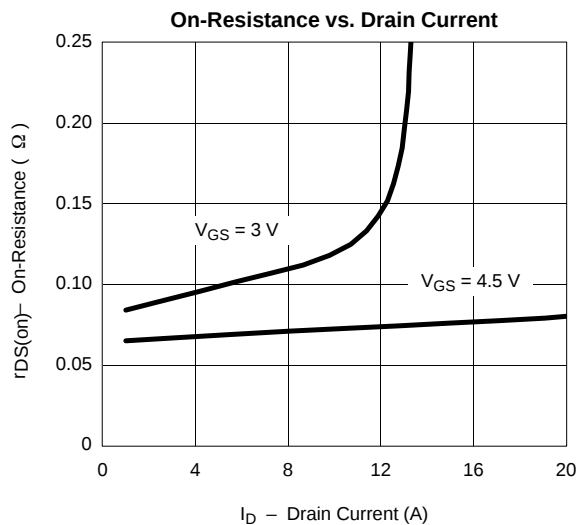
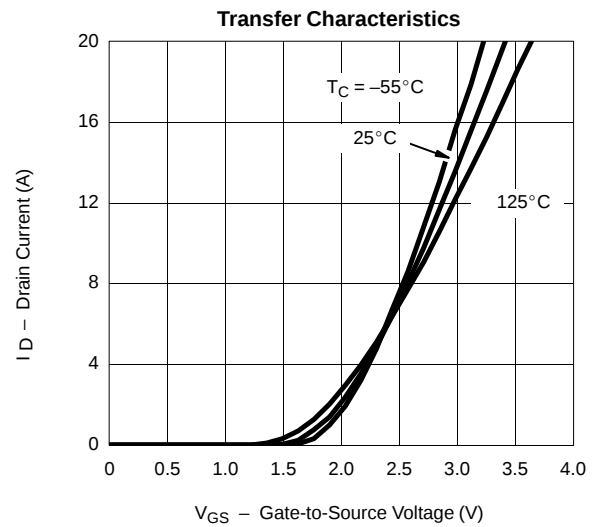
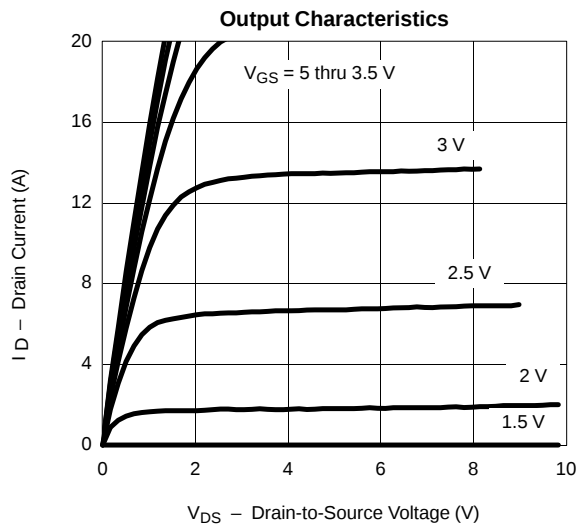
N-CHANNEL





TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

P-CHANNEL



TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

P-CHANNEL

